

102567-2 ✓ ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 102567-2

PCB Mount Header, Vertical, Board-to-Board, 24 Position, 2.54 mm  
[.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder,  
AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



EU RoHS Compliance: **Not Compliant**

EU ELV Compliance: **Compliant with Exemptions**

PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

## Features

### Contact Features

	100 $\mu$ m
PCB Contact Termination Area Plating Material Finish	Bright
Contact Mating Area Plating Material Thickness	.381 $\mu$ m[15 $\mu$ m]
Mating Square Post Dimension	.64 mm[.025 in]
Contact Shape & Form	Square
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3 A

### Other

EU RoHS Compliance	Not Compliant
EU ELV Compliance	Compliant with Exemptions

### Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Connector & Contact Terminates To	Printed Circuit Board



### Configuration Features

Board-to-Board Configuration	Parallel
PCB Mount Orientation	Vertical
Number of Positions	24
Number of Rows	2

### Electrical Characteristics

Operating Voltage	250 VAC
Termination Resistance	12 mΩ

### Body Features

Primary Product Color	Black
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### Termination Features

Termination Post & Tail Length	4.57 mm[.18 in]
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Method to PCB	Through Hole - Solder

### Mechanical Attachment

Mating Retention	Without
Mating Alignment Type	Guide Pins
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	With

### Housing Features

Housing Material	Thermoplastic
Centerline (Pitch)	2.54 mm[.1 in]

### Dimensions

Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	11.43 mm[.45 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Connector Height	13.97 mm[.55 in]

### Usage Conditions

Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
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### Operation/Application



Solder Process Feature	Board Standoff
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Circuit Application	Signal
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### Industry Standards

Compatible With Approved Standards Products	UL E28476, CSA LR7189
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UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	48
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Packaging Method	Tube
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Not Compliant
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EU ELV Directive 2000/53/EC	Compliant with Exemptions
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China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	<p>Current ECHA Candidate List: JUNE 2024 (241)</p> <p>Candidate List Declared Against: JUNE 2024 (241)</p> <p>SVHC &gt; Threshold:</p> <p>Pb (13% in Component Part)</p>
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**Article Safe Usage Statements:**

Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.

Halogen Content	BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.
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Solder Process Capability	Wave solder capable to 240°C
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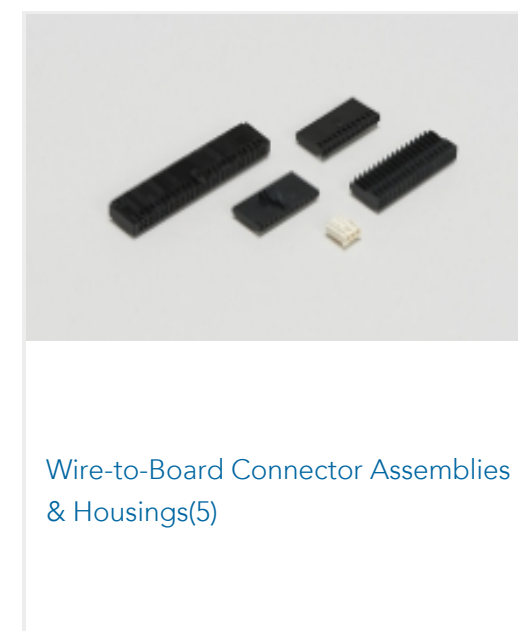
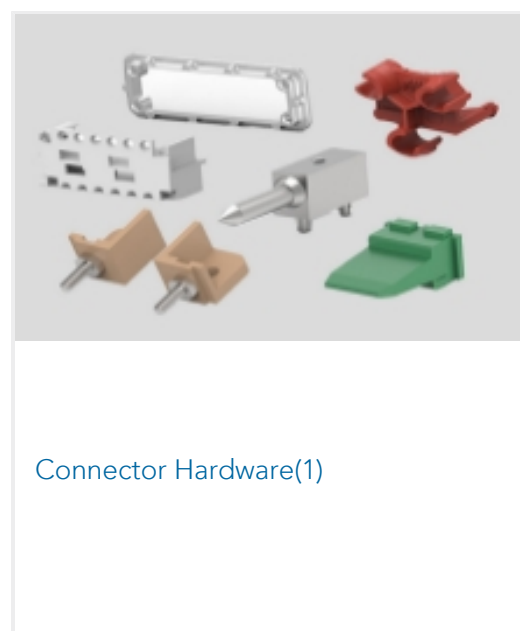
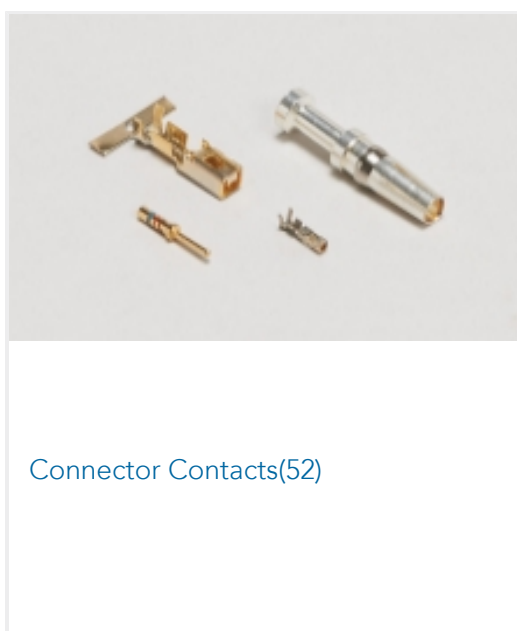
#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



## Also in the Series | AMPMODU Headers



## Customers Also Bought

### Documents

#### Product Drawings

[24 MODII 2PC HDR DR SHRD .100](#)

English

#### CAD Files

Customer View Model

[ENG\\_CVM\\_102567-2\\_N3.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_102567-2\\_N3.3d\\_stp.zip](#)

English

Customer View Model

[ENG\\_CVM\\_102567-2\\_N3.2d\\_dxf.zip](#)

English

[3D PDF](#)

3D

[3D PDF](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

#### Datasheets & Catalog Pages

[AMPMODU Interconnection System](#)

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PCB Mount Header, Vertical, Board-to-Board, 24 Position, 2.54 mm [.1 in] Centerline,  
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## AMPMODU Interconnection System

English